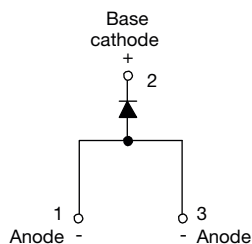




Surface Mount Fast Soft Recovery Rectifier Diode, 10 A



FEATURES

- Glass passivated pellet chip junction
- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- Designed and qualified according to JEDEC®-JESD 47
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

- Output rectification and freewheeling in inverters, choppers and converters
- Input rectifications where severe restrictions on conducted EMI should be met

DESCRIPTION

The VS-10ETF..S-M3 fast soft recovery rectifier series has been optimized for combined short reverse recovery time and low forward voltage drop.

The glass passivation ensures stable reliable operation in the most severe temperature and power cycling conditions.

PRIMARY CHARACTERISTICS

$I_{F(AV)}$	10 A
V_R	1000 V, 1200 V
V_F at I_F	1.33 V
I_{FSM}	155 A
t_{rr}	80 ns
T_J max.	150 °C
Snap factor	0.6
Package	D²PAK (TO-263AB)
Circuit configuration	Single

MAJOR RATINGS AND CHARACTERISTICS

SYMBOL	CHARACTERISTICS	VALUES	UNITS
$I_{F(AV)}$	Sinusoidal waveform	10	A
V_{RRM}		1000, 1200	V
I_{FSM}		155	A
V_F	10 A, $T_J = 25$ °C	1.33	V
t_{rr}	1 A, 100 A/μs	80	ns
T_J	Range	-40 to +150	°C

VOLTAGE RATINGS

PART NUMBER	V_{RRM} , MAXIMUM PEAK REVERSE VOLTAGE V	V_{RSM} , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	I_{RRM} AT 150 °C mA
VS-10ETF10S-M3	1000	1100	4
VS-10ETF12S-M3	1200	1300	

ABSOLUTE MAXIMUM RATINGS

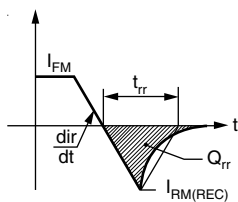
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum average forward current	$I_{F(AV)}$	$T_C = 125$ °C, 180° conduction half sine wave	10	A
Maximum peak one cycle non-repetitive surge current	I_{FSM}	10 ms sine pulse, rated V_{RRM} applied	130	
		10 ms sine pulse, no voltage reapplied	155	
Maximum I^2t for fusing	I^2t	10 ms sine pulse, rated V_{RRM} applied	85	A²s
		10 ms sine pulse, no voltage reapplied	120	
Maximum $I^2\sqrt{t}$ for fusing	$I^2\sqrt{t}$	$t = 0.1$ ms to 10 ms, no voltage reapplied	1200	A²√s

**ELECTRICAL SPECIFICATIONS**

PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum forward voltage drop	V_{FM}	10 A, $T_J = 25\text{ }^{\circ}\text{C}$		1.33	V
Forward slope resistance	r_t	$T_J = 150\text{ }^{\circ}\text{C}$		22.9	m Ω
Threshold voltage	$V_{F(TO)}$			0.96	V
Maximum reverse leakage current	I_{RM}	$T_J = 25\text{ }^{\circ}\text{C}$	$V_R = \text{rated } V_{RRM}$	0.1	mA
		$T_J = 150\text{ }^{\circ}\text{C}$		4	

RECOVERY CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Reverse recovery time	t_{rr}	I_F at 10 A _{pk} 25 A/ μ s 25 $^{\circ}\text{C}$	310	ns
Reverse recovery current	I_{rr}		4.7	A
Reverse recovery charge	Q_{rr}		1.05	μ C
Typical snap factor	S		0.6	

**THERMAL - MECHANICAL SPECIFICATIONS**

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction and storage temperature range	T_J, T_{Stg}		-40 to +150	$^{\circ}\text{C}$
Maximum thermal resistance, junction to case	R_{thJC}	DC operation	1.5	$^{\circ}\text{C/W}$
Maximum thermal resistance, junction to ambient (PCB mount)	$R_{thJA}^{(1)}$		62	
Approximate weight			2	g
			0.07	oz.
Marking device		Case style D ² PAK (TO-263AB)	10ETF10S	
			10ETF12S	

Note

⁽¹⁾ When mounted on 1" square (650 mm²) PCB of FR-4 or G-10 material 4 oz. (140 μ m) copper 40 $^{\circ}\text{C/W}$. For recommended footprint and soldering techniques refer to application note #AN-994

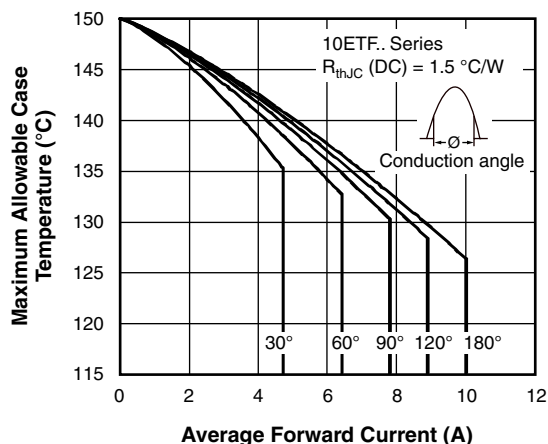


Fig. 1 - Current Rating Characteristics

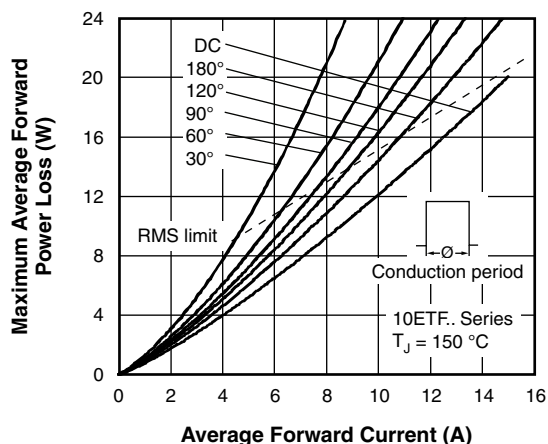


Fig. 4 - Forward Power Loss Characteristics

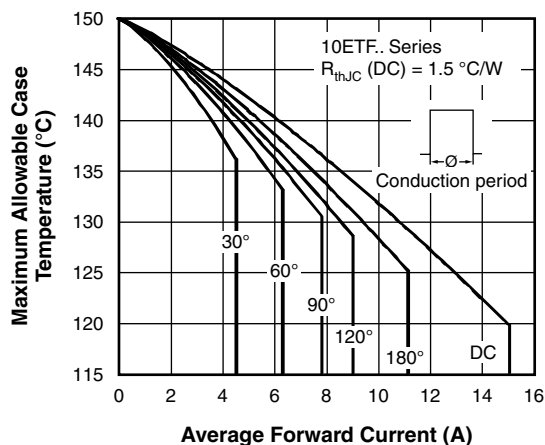


Fig. 2 - Current Rating Characteristics

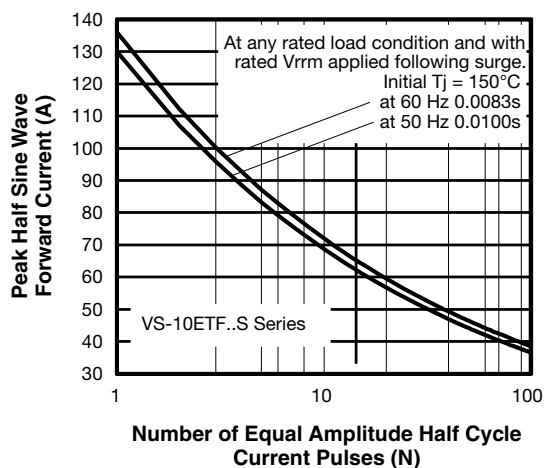


Fig. 5 - Maximum Non-Repetitive Surge Current

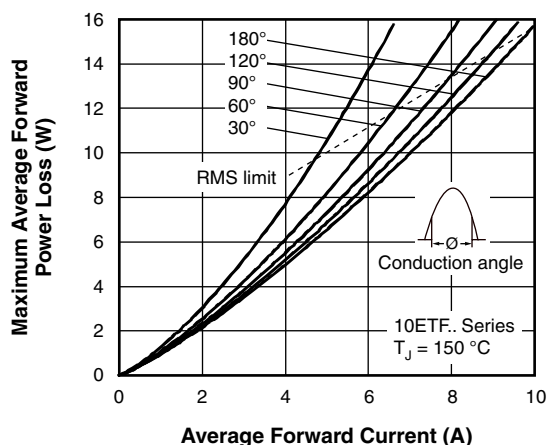


Fig. 3 - Forward Power Loss Characteristics

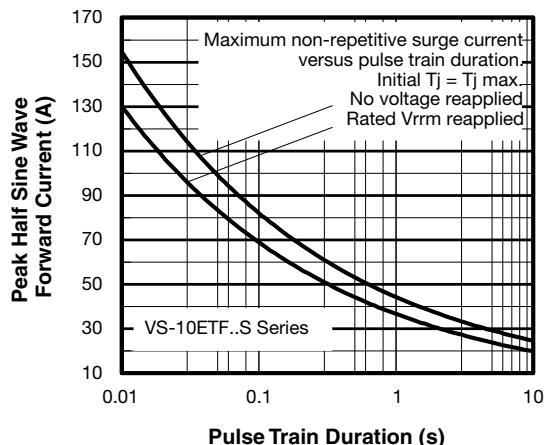


Fig. 6 - Maximum Non-Repetitive Surge Current

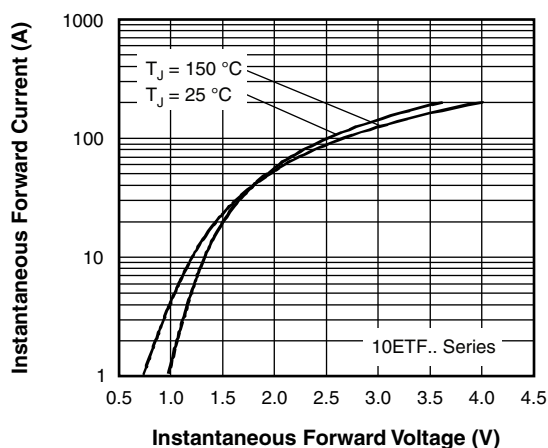
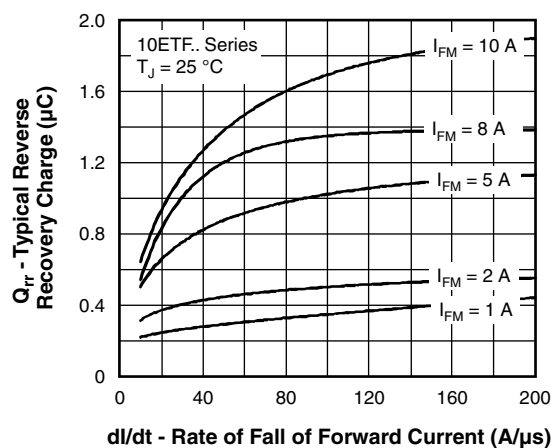
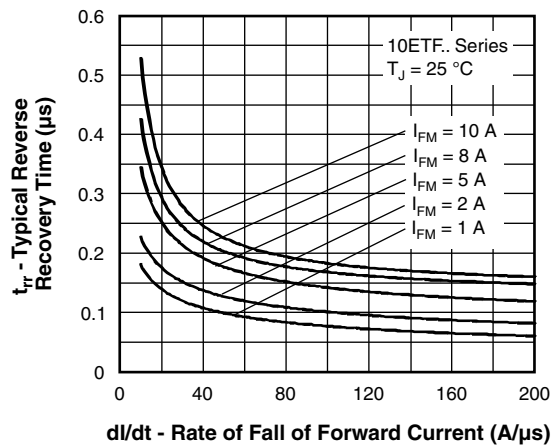
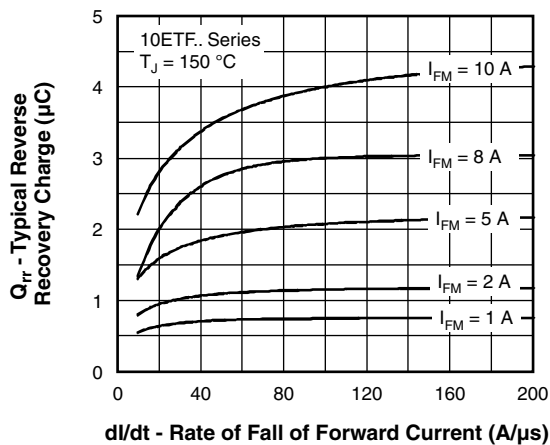
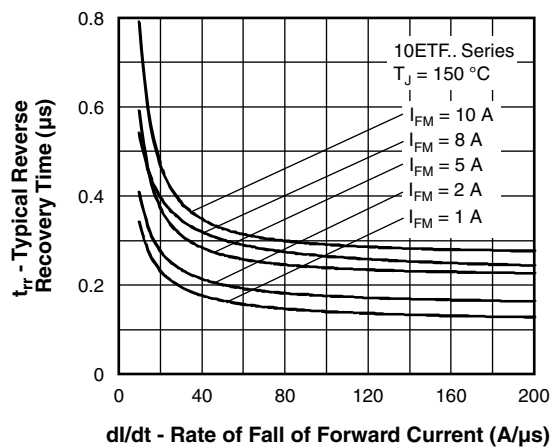
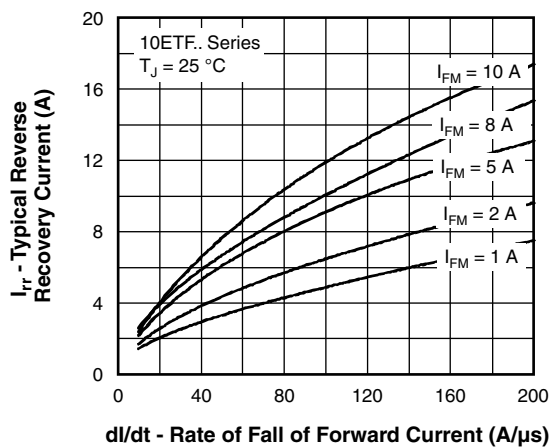


Fig. 7 - Forward Voltage Drop Characteristics


Fig. 10 - Recovery Charge Characteristics, $T_J = 25\text{ }^{\circ}\text{C}$

Fig. 8 - Recovery Time Characteristics, $T_J = 25\text{ }^{\circ}\text{C}$

Fig. 11 - Recovery Charge Characteristics, $T_J = 150\text{ }^{\circ}\text{C}$

Fig. 9 - Recovery Time Characteristics, $T_J = 150\text{ }^{\circ}\text{C}$

Fig. 12 - Recovery Current Characteristics, $T_J = 25\text{ }^{\circ}\text{C}$

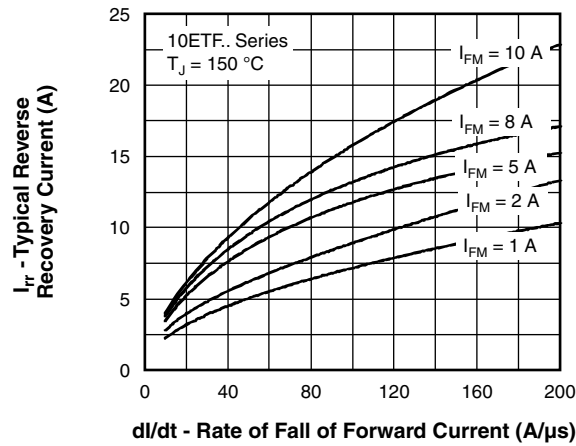


Fig. 13 - Recovery Current Characteristics, $T_J = 150\text{ }^{\circ}\text{C}$

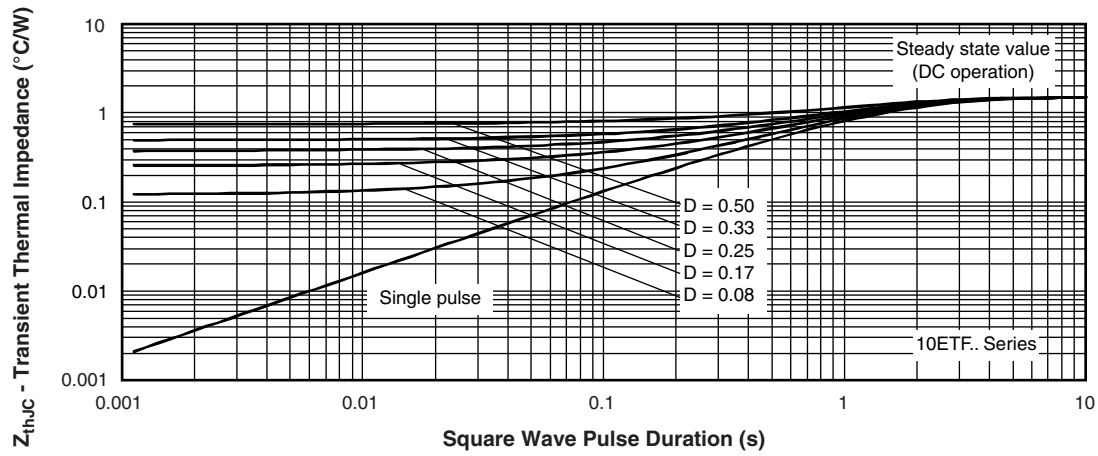


Fig. 14 - Thermal Impedance Z_{thJC} Characteristics

ORDERING INFORMATION TABLE

Device code	VS-	10	E	T	F	12	S	TRL	-M3
	1	2	3	4	5	6	7	8	9

- 1 - Vishay Semiconductors product
- 2 - Current rating (10 = 10 A)
- 3 - Circuit configuration:
E = single
- 4 - Package:
T = D²PAK (TO-263AB)
- 5 - Type of silicon:
F = fast soft recovery rectifier
- 6 - Voltage code x 100 = V_{RRM} 10 = 1000 V
12 = 1200 V
- 7 - S = surface mountable
- 8 -
 - None = tube
 - TRR = tape and reel (right oriented)
 - TRL = tape and reel (left oriented)
- 9 - -M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)		
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION
VS-10ETF10S-M3	50	Antistatic plastic tubes
VS-10ETF10STRR-M3	800	13" diameter reel
VS-10ETF10STRL-M3	800	13" diameter reel
VS-10ETF12S-M3	50	Antistatic plastic tubes
VS-10ETF12STRR-M3	800	13" diameter reel
VS-10ETF12STRL-M3	800	13" diameter reel

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?96164
Part marking information	www.vishay.com/doc?95444
Packaging information	www.vishay.com/doc?96424



D²PAK

DIMENSIONS in millimeters and inches

Conforms to JEDEC® outline D²PAK (SMD-220)



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190	
A1	0.00	0.254	0.000	0.010	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
c	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
e	2.54 BSC		0.100 BSC		
H	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	-	0.066	3
L2	1.27	1.78	0.050	0.070	
L3	0.25 BSC		0.010 BSC		
L4	4.78	5.28	0.188	0.208	

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inches
- (7) Outline conforms to JEDEC® outline TO-263AB



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